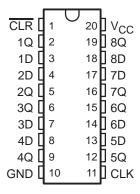
- EPIC™ (Enhanced-Performance Implanted CMOS) 2-µ Process
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC.} T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 > 2 V at V_{CC}, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Flat (W) Packages, Chip Carriers (FK), and (J) 300-mil DIPs

description

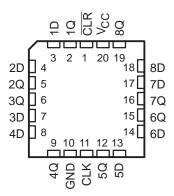
These octal D-type flip-flops are designed for 2.7-V to 5.5-V V_{CC} operation.

The 'LV273 are positive-edge-triggered flip-flops with direct clear (CLR) input. Information at the data (D) inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock (CLK) input is at either the high or low level, the D-input signal has no effect at the output.

SN54LV273 . . . J OR W PACKAGE SN74LV273 . . . DB, DW, OR PW PACKAGE (TOP VIEW)



SN54LV273 . . . FK PACKAGE (TOP VIEW)



The SN74LV273 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54LV273 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74LV273 is characterized for operation from -40° C to 85° C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

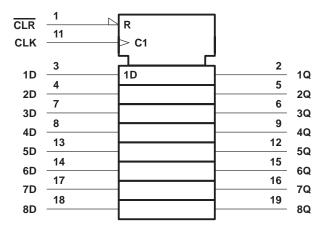
EPIC is a trademark of Texas Instruments Incorporated.



FUNCTION TABLE (each flip-flop)

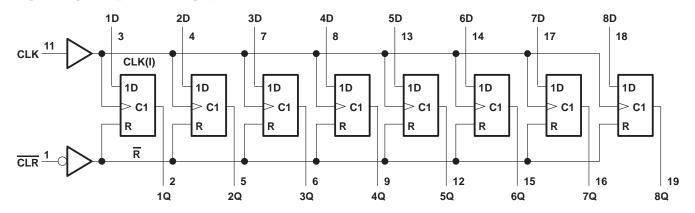
	INPUTS		OUTPUT
CLR	CLK	D	Q
L	Х	Χ	L
Н	\uparrow	Н	Н
Н	\uparrow	L	L
Н	L	Χ	Q ₀

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for DB, DW, J, PW, and W packages.

logic diagram (positive logic)





SCLS195B - FEBRUARY 1993 - REVISED APRIL 1996

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 7 V
Input voltage range, V _I (see Note 1)		\dots -0.5 V to V _{CC} + 0.5 V
Output voltage range, VO (see Notes 1 and 2)		\dots -0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)		±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})		±50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$		±25 mA
Continuous current through V _{CC} or GND		±50 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note	3): DB package	0.6 W
	DW package	1.6 W
	PW package	0.7 W
Storage temperature range, T _{sto}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 7 V maximum.
- 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 4)

			SN54L	V273	SN74L	V273	UNIT
				MAX	MIN	MAX	UNII
Vсс	Supply voltage		2.7	5.5	2.7	5.5	V
V	High level input voltege	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		2		V
VIH	High-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	3.15		3.15		V
\/	Low level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		0.8	V
VIL	Low-level input voltage $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$			1.65		1.65	V
٧ı	Input voltage		0	Vcc	0	VCC	V
Vo	Output voltage		0	VCC	0	VCC	V
lou	High lovel output ourrent	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	20	-6		-6	mA
ЮН	High-level output current	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	140	-12		-12	IIIA
la.	Low lovel entropy ourrent	V _{CC} = 2.7 V to 3.6 V	V	6		6	mA
IOL	Low-level output current		12		12	mA	
Δt/Δν	Input transition rise or fall rate		0	100	0	100	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	., +	SN	54LV27	'3	SN	174LV27	'3	UNIT
PARAMETER	TEST CONDITIONS	v _{CC} †	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
	I _{OH} = -100 μA	MIN to MAX	V _{CC} -0.	2		V _{CC} -0.	.2		
Voн	$I_{OH} = -6 \text{ mA}$	3 V	2.4			2.4			V
	I _{OH} = -12 mA	4.5 V	3.6			3.6			
	I _{OL} = 100 μA	MIN to MAX			0.2			0.2	
VOL	I _{OL} = 6 mA	3 V			0.4			0.4	V
	I _{OL} = 12 mA	4.5 V			0.55			0.55	
1.	V _I = V _{CC} or GND	3.6 V			₹ ±1			±1	μΑ
II.	AL = ACC OL GIAD	5.5 V		ZEL	±1			±1	μΑ
loz	$V_O = V_{CC}$ or GND, $I_O = 0$	3.6 V		2	±5			±5	μΑ
loz	VQ = VCC of GND, $IQ = 0$	5.5 V		Ç,	±5			±5	μΑ
loo	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V	9 _C		20			20	
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V	Q Z		20			20	μΑ
∆ICC	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			500			500	μА
Ci	V _I = V _{CC} or GND	3.3 V		2.5		2.5			pF
	AL = ACC OL GIAD	5 V		3			3		ρr

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

				SN54LV273						
			V _{CC} = ± 0.		V _{CC} =		V _{CC} =	2.7 V	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX		
fclock	Clock frequency		0	60	. 0	50	₹ 0	40	MHz	
	Pulse duration	CLR low	6	-01	10		12		no	
t _W	CLK high or low		7	OP.	10	S.P.O	12		ns	
	Catura time a hafana CLKA	Data	8	, 6 _k	12	, <	14		20	
t _{su}	Setup time before CLK↑		2		2		2		ns	
t _h	Hold time, data after CLK↑	•	3		2		2		ns	

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			SN74LV273						
		$V_{CC} = 5.5 \text{ V}$ $V_{CC} = 3.3 \text{ V}$ $\pm 0.5 \text{ V}$ $\pm 0.3 \text{ V}$ $V_{CC} = 2.7 \text{ V}$		2.7 V	UNIT				
			MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency		0	60	0	50	0	40	MHz
	Pulse duration	CLR low	6		10		12		no
t _W	CLK high or low		7		10		12		ns
	Satura time a historia CLIVA	Data	8		12		14		
t _{su}	Setup time before CLK↑ CLR inactive		2	2			2		ns
t _h	Hold time, data after CLK↑		3		2		2		ns

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switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER						SN54L	.V273					
	PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} :	= 5 V ± ().5 V	V _{CC} =	3.3 V ±	0.3 V	V _{CC} =	2.7 V	UNIT
	(INFOT) (COTFOT)	MIN	TYP	MAX	MIN	TYP	MAX	_ MIN	MAX			
f _{max}			60	100		50	80	N	40		MHz	
^t pd	CLK	Q		11	16	JIE.	16	22	JIE.	26	ns	
t _{PHL}	CLR	Q		13	22		14	24		30	ns	

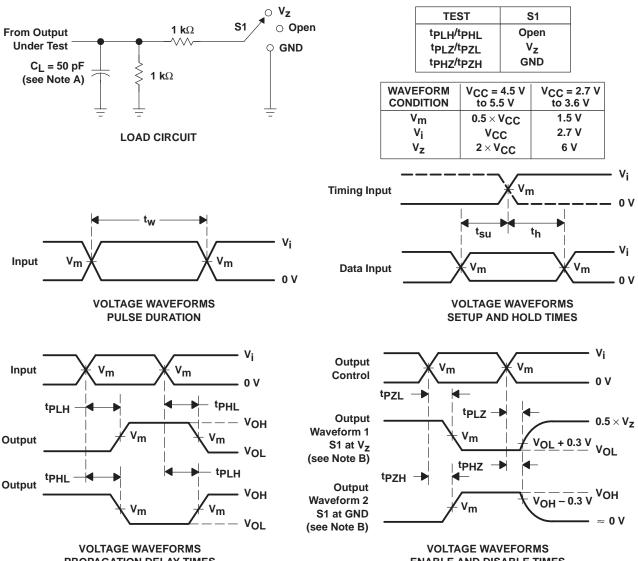
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

			SN74LV273								
PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC:	= 5 V ± 0).5 V	V _{CC} =	3.3 V \pm	0.3 V	VCC =	2.7 V	UNIT
	(INFOT) (COTFOT)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	MAX		
fmax			60	100		50	80		40		MHz
^t pd	CLK	Q		11	16		16	22		26	ns
t _{PHL}	CLR	Q		13	22		14	24		30	ns

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	VCC	TYP	UNIT
Co.d. Down	Power discipation canacitance per flip flep	C ₁ = 50 pF, f = 10 MHz	3.3 V	32	ρF
Cpd	Power dissipation capacitance per flip-flop	C[= 30 pr, T = 10 WH2	5 V	41	РΓ

PARAMETER MEASUREMENT INFORMATION



PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS

ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_f \leq 2.5 \ ns$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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